

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSOT-23

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**TOTAL MASS (g) : 0.012007**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000418	1000000	34813.921875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	381620.5625		
		Iron (Fe)	7439-89-6	0.000113	24000	9411.41992188		
		Phosphorus (P)	7723-14-0	0.000001	300	83.286895752		
		Zinc (Zn)	7440-66-6	0.000003	700	249.860687256		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004699</b>	<b>1000000</b>	<b>391365.15625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000663	1000000	55193.390625		
		<b>External Plating Total:</b>				<b>0.000663</b>	<b>1000000</b>	<b>55193.390625</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000080	1000000	6662.95117188		
<b>Internal Plating Total:</b>				<b>0.000080</b>	<b>1000000</b>	<b>6662.95117188</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000004	50000	333.147583008		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000024	300000	1998.88549805		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000051	650000	4247.63134766		
<b>Die Attach Total:</b>				<b>0.000079</b>	<b>1000000</b>	<b>6579.66455078</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000777	130000	64713.9179688		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.004963	830000	413352.84375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000209	35000	17406.9609375		
		Carbon Black (C)	1333-86-4	0.000030	5000	2498.60693359		
		<b>Encapsulation Total:</b>				<b>0.005979</b>	<b>1000000</b>	<b>497972.375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000089	1000000	7412.53369141		
					<b>TOTAL MASS (g) :</b>	<b>0.012007</b>		